



OptiSIM

Thinnest SIM card with natural color

Tailored for low-end SIM requirements, Linxens OptiSIM is based on UltraSIM plating configuration, also equipped with an additional cavity and alternative epoxy glass substrate. OptiSIM is our most optimized product for the telecom market.

Key Features

- Nano-protection of Gold on contact surface preventing nickel oxidation and allergies
- The most optimized plating configuration in SIM card
- Visual appearance on contact surface remains yellowish
- Basic corrosion resistance
- Design made with cavity

Typical Product Designs

Solution	Part Number	Modules	Chip Dimension	Cavity
4FF	9X13101	6	2.5 x 2.5 mm	✓
4FF	9X12420	6	1.8 x 1.8 mm	✓
4FF	9X21005	6	3.9 x 4.9 mm	✓
4FF	9X25301	6	3.1 x 3.6 mm	✓
2FF/3FF/4FF	9X12416	6	1.8 x 1.8 mm	✓



MICROCONNECTORS



Overview

Material

- Film base: Alternative Epoxy glass (Natural color)
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29 μ

Thickness

- Total: 159 \pm 20 μ m
- Plating Thickness
 - Contact side:
 - Ni: 1.2 \pm 0.3 μ m
 - Au: Nano-protection
 - Back side:
 - Ni: 5 (-2 +3) μ m
 - Au: 0.25 (-0.10 +0.20) μ m
- Cavity: Yes

Plating Performance

Basic corrosion resistance

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- Telecom

Options

- 4FF only